

μPD5904T7K

Data Sheet

R09DS0045EJ0200

Rev.2.00

Dec 11, 2012

CMOS Integrated Circuits High Power SP4T Switch

DESCRIPTION

The μPD5904T7K is a CMOS MMIC SP4T (Single Pole Four Throw) switch for GSM and UMTS/LTE main Antenna switching and other High Power RF switching applications up to +35 dBm.

This device can operate frequency from 0.05 to 6.0 GHz, having low insertion loss and high isolation.

This device is housed in a 12-pin plastic QFN (Quad Flat Non-Leaded) (T7K) package.

FEATURES

- Low control voltage : $V_{cont} = 1.3 \text{ V MIN.}, V_{DD} = 2.3 \text{ V MIN.}$
- Low insertion loss : $L_{ins} = 0.4 \text{ dB TYP. @ } f = 1 \text{ GHz}$
 $L_{ins} = 0.5 \text{ dB TYP. @ } f = 2 \text{ GHz}$
- High isolation : $ISL = 35 \text{ dB TYP. @ } f = 1 \text{ GHz}$
 $ISL = 30 \text{ dB TYP. @ } f = 2 \text{ GHz}$
- High Handling power : $P_{in(0.1dB)} = +38 \text{ dBm TYP. @ } f = 0.9/2 \text{ GHz}$
- High-density surface mounting : 12-pin plastic QFN (T7K) package (2.0 × 2.0 × 0.6 mm)
- No DC blocking capacitors required.

APPLICATIONS

- GSM and UMTS/LTE main Antenna switching
- Diversity Antenna switching
- Antenna tuning Application

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPD5904T7K-E2	μPD5904T7K-E2-A	12-pin plastic QFN (T7K) (Pb-Free)	5904	• Embossed tape 8 mm wide • Pin 10, 11 and 12 face the perforation side of the tape • Qty 3 kpcs/reel

Remark To order evaluation samples, please contact your nearby sales office.

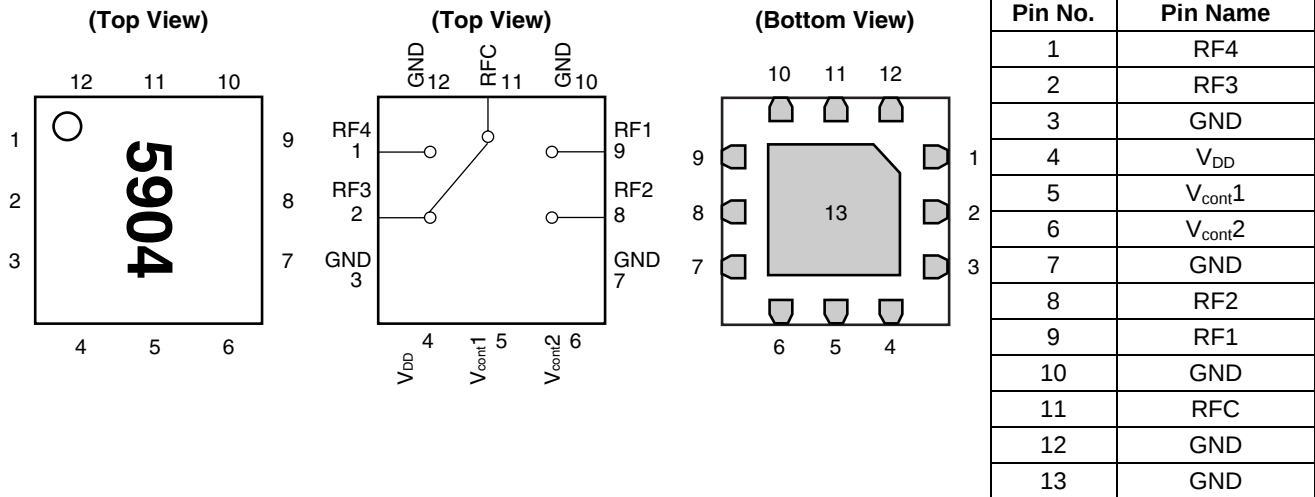
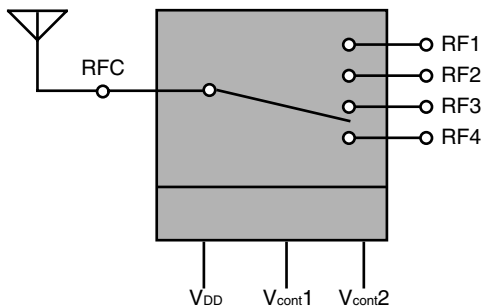
Part number for sample order: μPD5904T7K-A

CAUTION

Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions must be employed at all times.

The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

<R> PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM**BLOCK DIAGRAM****SW TRUTH TABLE**

V _{cont1}	V _{cont2}	RFC–RF1	RFC–RF2	RFC–RF3	RFC–RF4
High	High	ON	OFF	OFF	OFF
High	Low	OFF	ON	OFF	OFF
Low	High	OFF	OFF	ON	OFF
Low	Low	OFF	OFF	OFF	ON

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	3.6	V
Control Voltage	V _{cont}	3.6	V
Input Power	P _{in}	+38	dBm
Operating Ambient Temperature	T _A	–40 to +85	°C
Storage Temperature	T _{stg}	–55 to +125	°C

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.05	–	6.0	GHz
Supply Voltage	V _{DD}	2.3	–	3.3	V
Control Voltage (High)	V _{cont (H)} ^{Note}	1.3	–	V _{DD}	V
Control Voltage (Low)	V _{cont (L)}	0	–	0.4	V

Note: V_{cont} ≤ V_{DD}

ELECTRICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{DD} = 2.5\text{ V}$, $V_{\text{cont (H)}} = 1.8\text{ V}$, $V_{\text{cont (L)}} = 0\text{ V}$, $Z_O = 50\ \Omega$, unless otherwise specified)

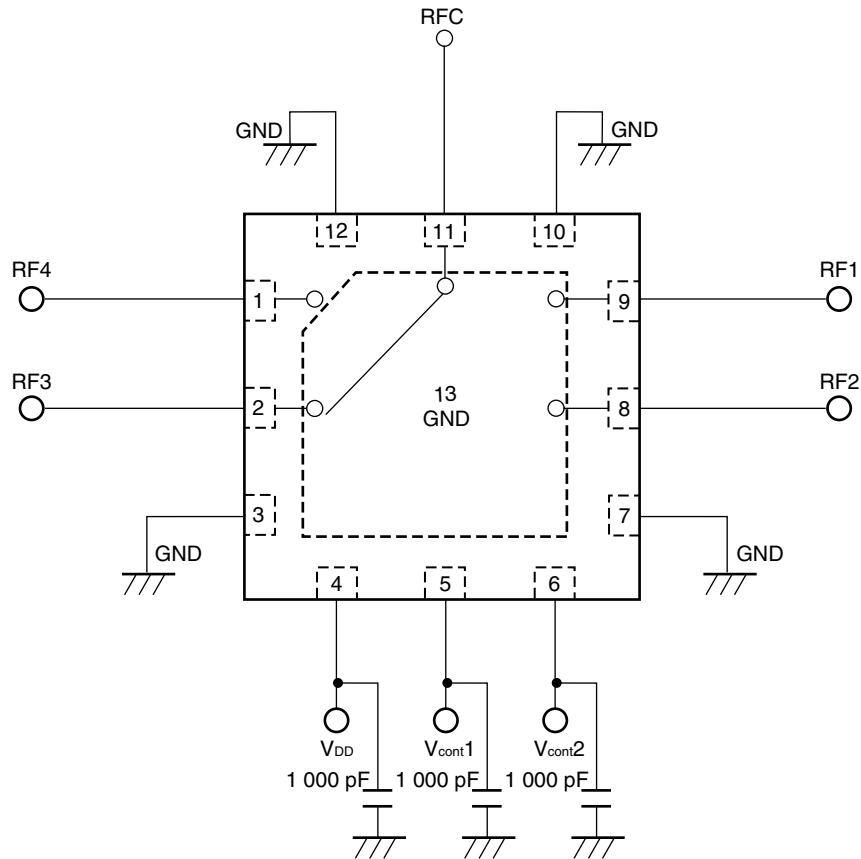
Parameter	Symbol	Path	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	$L_{\text{ins}1}$	RFC –	$f = 0.05\text{ to }0.5\text{ GHz}$	–	0.35	0.50	dB
	$L_{\text{ins}2}$	RF1, 2, 3, 4	$f = 0.5\text{ to }1.0\text{ GHz}$	–	0.40	0.55	dB
	$L_{\text{ins}3}$		$f = 1.0\text{ to }2.0\text{ GHz}$	–	0.50	0.65	dB
	$L_{\text{ins}4}$		$f = 2.0\text{ to }2.7\text{ GHz}$	–	0.55	0.75	dB
	$L_{\text{ins}5}$		$f = 2.7\text{ to }3.8\text{ GHz}$	–	0.60	0.80	dB
	$L_{\text{ins}6}$		$f = 3.8\text{ to }6.0\text{ GHz}$	–	0.75	0.95	dB
Isolation	ISL1	RFC –	$f = 0.05\text{ to }0.5\text{ GHz}$	30	40	–	dB
	ISL2	RF1, 2, 3, 4	$f = 0.5\text{ to }1.0\text{ GHz}$	25	35	–	dB
	ISL3		$f = 1.0\text{ to }2.0\text{ GHz}$	20	30	–	dB
	ISL4		$f = 2.0\text{ to }2.7\text{ GHz}$	15	25	–	dB
	ISL5		$f = 2.7\text{ to }3.8\text{ GHz}$	15	25	–	dB
	ISL6		$f = 3.8\text{ to }6.0\text{ GHz}$	10	20	–	dB
Return Loss (RFC)	$RL_{(C)1}$	RFC –	$f = 0.05\text{ to }3.8\text{ GHz}$	15	25	–	dB
	$RL_{(C)2}$	RF1, 2, 3, 4	$f = 3.8\text{ to }6.0\text{ GHz}$	10	17	–	dB
Return Loss (RF1,2,3,4)	$RL_{(RF)1}$		$f = 0.05\text{ to }3.8\text{ GHz}$	15	25	–	dB
	$RL_{(RF)2}$		$f = 3.8\text{ to }6.0\text{ GHz}$	10	17	–	dB
0.1 dB Loss Compression Input Power	$P_{\text{in (0.1 dB)1}}$	RFC – RF1, 2, 3, 4	$f = 0.9\text{ GHz}$	+36.0	+38.0 Note	–	dBm
	$P_{\text{in (0.1 dB)2}}$		$f = 2.0\text{ GHz}$	+36.0	+38.0 Note	–	dBm
Harmonics	2f0 (L)	RFC –	$f = 0.9\text{ GHz}$,	75	80	–	dBc
	3f0 (L)	RF1, 2, 3, 4	$P_{\text{in}} = +35\text{ dBm CW}$	70	75	–	
	2f0 (H)	RFC –	$f = 2.0\text{ GHz}$,	75	85	–	dBc
	3f0 (H)	RF1, 2, 3, 4	$P_{\text{in}} = +33\text{ dBm CW}$	70	80	–	
2nd Order Inter Modulation Distortion	IMD2(L)	RFC – RF1, 2, 3, 4	$f = 835\text{ MHz}$, $P_{\text{in}} = +20\text{ dBm}$ $f = 45\text{ MHz}$, $P_{\text{in}} = -15\text{ dBm}$	–	-98	-93	dBc
	IMD2(H)		$f = 1\ 950\text{ MHz}$, $P_{\text{in}} = +20\text{ dBm}$ $f = 190\text{ MHz}$, $P_{\text{in}} = -15\text{ dBm}$	–	-105	-100	
3rd Order Inter Modulation Distortion	IMD3(L)	RFC – RF1, 2, 3, 4	$f = 835\text{ MHz}$, $P_{\text{in}} = +20\text{ dBm}$ $f = 790\text{ MHz}$, $P_{\text{in}} = -15\text{ dBm}$	–	-110	-105	dBc
	IMD3(H)		$f = 1\ 950\text{ MHz}$, $P_{\text{in}} = +20\text{ dBm}$ $f = 1\ 760\text{ MHz}$, $P_{\text{in}} = -15\text{ dBm}$	–	-110	-105	
Triple Beat Ratio	TBR(L)	RFC – RF1, 2, 3, 4	$f = 836 \pm 0.5\text{ MHz}$, $P_{\text{in}} = +21.5\text{ dBm}$ $f = 881.5\text{ MHz}$, $P_{\text{in}} = -30\text{ dBm}$	75	80	–	dBc
	TBR(H)		$f = 1\ 880.5 \pm 0.5\text{ MHz}$, $P_{\text{in}} = +21.5\text{ dBm}$ $f = 1\ 960\text{ MHz}$, $P_{\text{in}} = -30\text{ dBm}$	75	80	–	
Input 2nd order Intercept Point	$IIP_{2(\text{Cel})}$	RFC – RF1, 2, 3, 4	$f = 836.6\text{ MHz}$, $P_{\text{in}} = +24\text{ dBm}$ $f = 1718\text{ MHz}$, $P_{\text{in}} = -20\text{ dBm}$	105	110	–	dBm
	$IIP_{2(\text{PCS})}$		$f = 1\ 885\text{ MHz}$, $P_{\text{in}} = +24\text{ dBm}$ $f = 3\ 850\text{ MHz}$, $P_{\text{in}} = -20\text{ dBm}$	105	110	–	

Note: Absolute Maximum Ratings

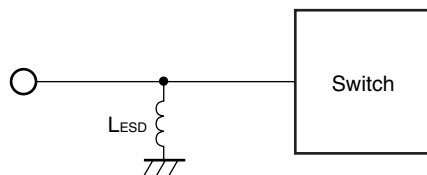
ELECTRICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{DD} = 2.5\text{ V}$, $V_{\text{cont (H)}} = 1.8\text{ V}$, $V_{\text{cont (L)}} = 0\text{ V}$, $Z_O = 50\ \Omega$, unless otherwise specified)

Parameter	Symbol	Path	Test Conditions	MIN.	TYP.	MAX.	Unit
Switch Control Speed	t_{sw}	RFC – RF1, 2, 3, 4	50% CTL to 90/10%	–	1.5	3	μs
Supply Current	I_{DD}	–	No RF	–	130	250	μA
Control Current 1	$I_{\text{cont1(H)}}$	–	V_{cont1} : High No RF	–	–	1	
	$I_{\text{cont1(L)}}$	–	V_{cont1} : Low No RF	–	–	1	
Control Current 2	$I_{\text{cont2(H)}}$	–	V_{cont2} : High No RF	–	–	1	
	$I_{\text{cont2(L)}}$	–	V_{cont2} : Low No RF	–	–	1	

<R> EVALUATION CIRCUIT

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

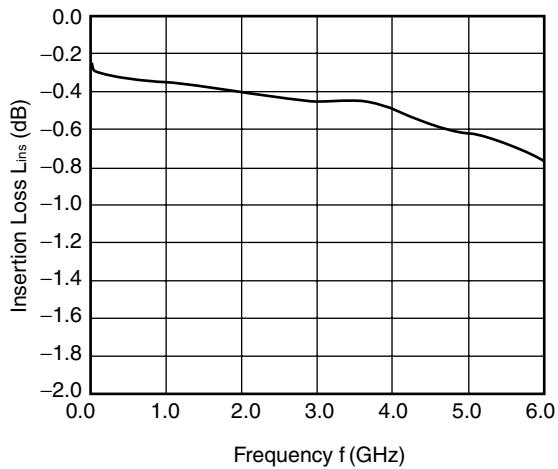
APPLICATION INFORMATION

- L_{ESD} provides a means to increase the ESD protection on a specific RF port, typically the port attached to the antenna.

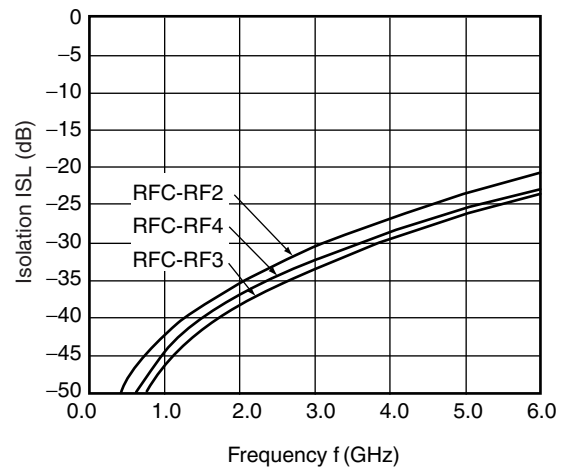
TYPICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{DD} = 2.5\text{ V}$, $V_{\text{cont (H)}} = 1.8\text{ V}$, $V_{\text{cont (L)}} = 0\text{ V}$, $Z_O = 50\ \Omega$, unless otherwise specified)

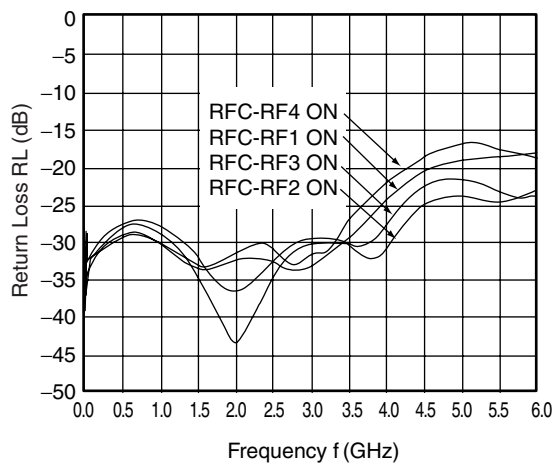
RFC-RF1/RF2/RF3/RF4
INSERTION LOSS vs. FREQUENCY



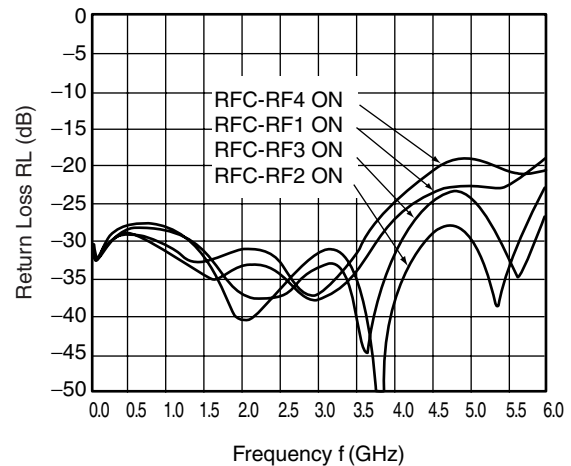
RFC-RF2/RF3/RF4 (RFC-RF1 ON)
ISOLATION vs. FREQUENCY



RFC RETURN LOSS vs. FREQUENCY

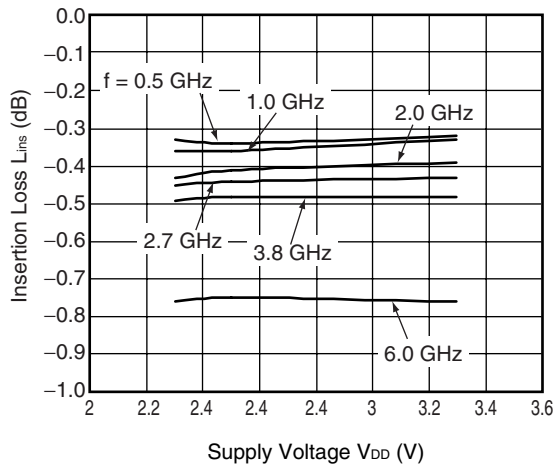


RF1/RF2/RF3/RF4 RETURN LOSS vs. FREQUENCY

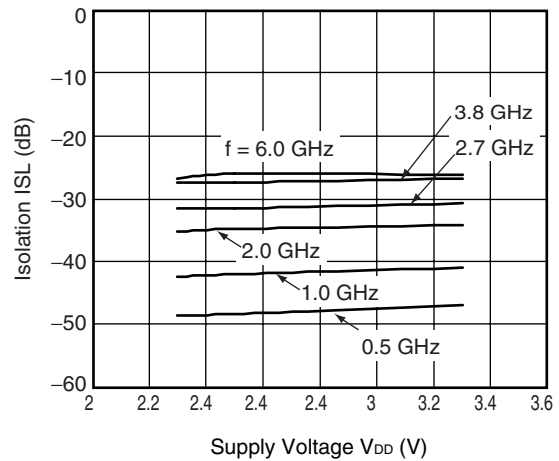


Remark The graphs indicate nominal characteristics.

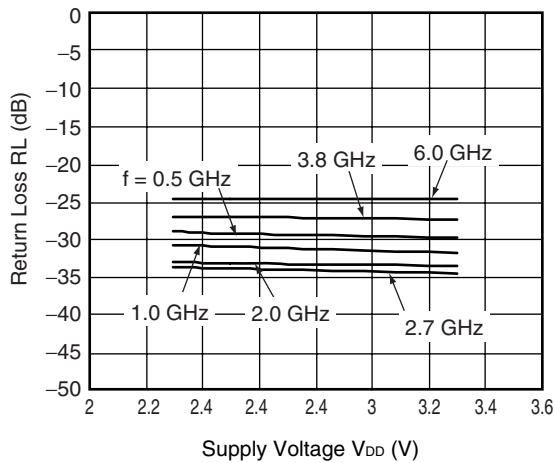
RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs. SUPPLY VOLTAGE



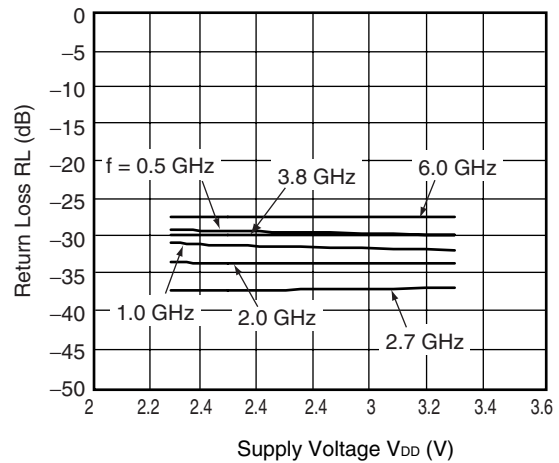
RFC-RF1/RF2/RF3/RF4 ISOLATION vs. SUPPLY VOLTAGE



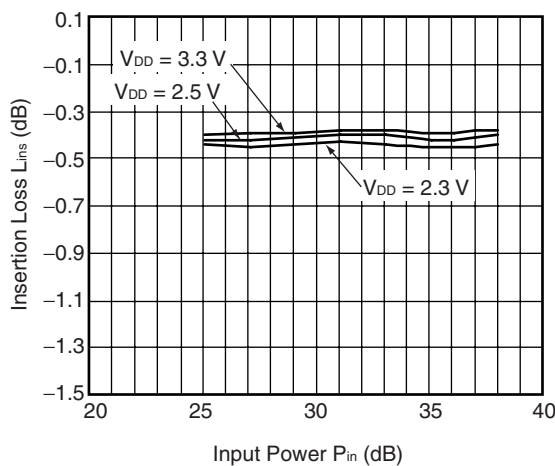
RFC-RF1/RF2/RF3/RF4 RETURN LOSS vs. SUPPLY VOLTAGE



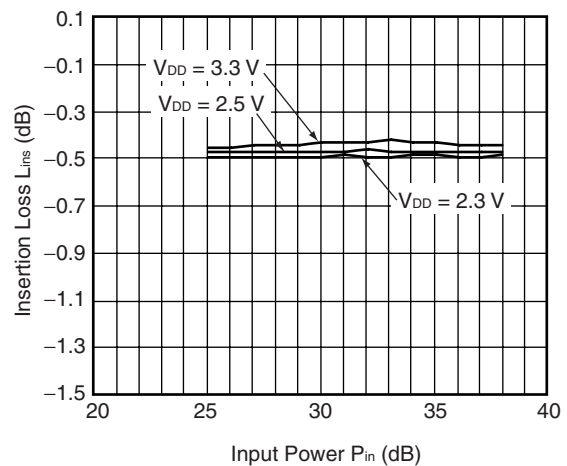
RF1/RF2/RF3/RF4-RFC RETURN LOSS vs. SUPPLY VOLTAGE



RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs. INPUT POWER f = 0.9 GHz

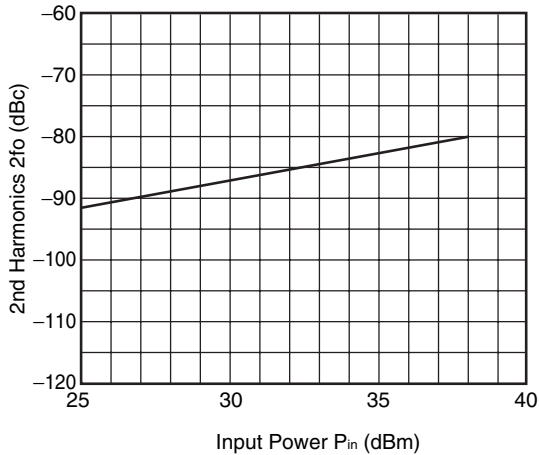


RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs. INPUT POWER f = 2 GHz

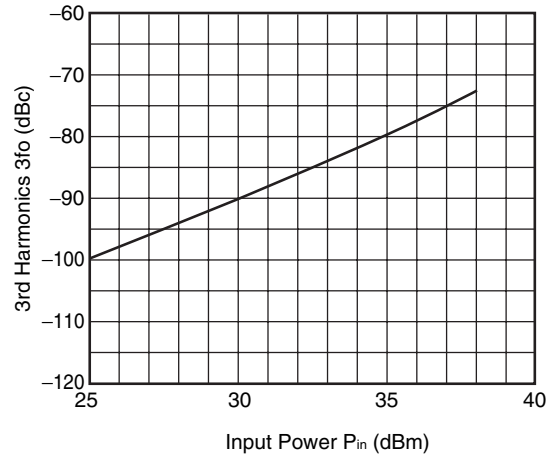


Remark The graphs indicate nominal characteristics.

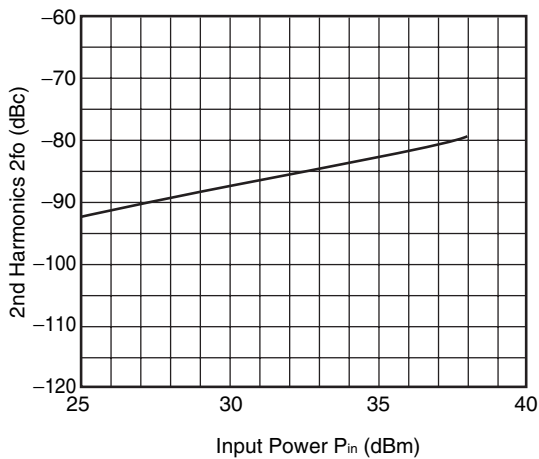
RFC-RF1/RF2/RF3/RF4 2nd HARMONICS vs.
INPUT POWER $f = 0.9$ GHz



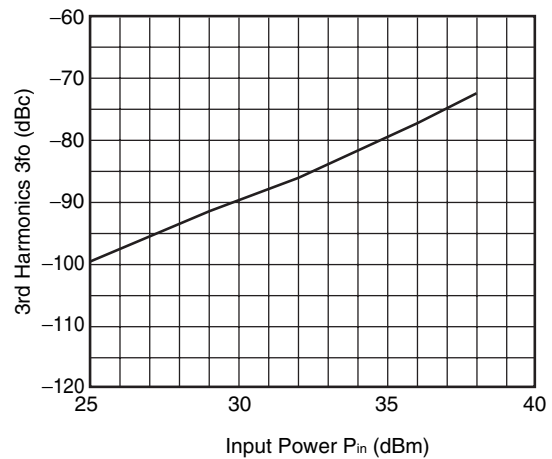
RFC-RF1/RF2/RF3/RF4 3rd HARMONICS $3f_o$ vs.
INPUT POWER $f = 0.9$ GHz



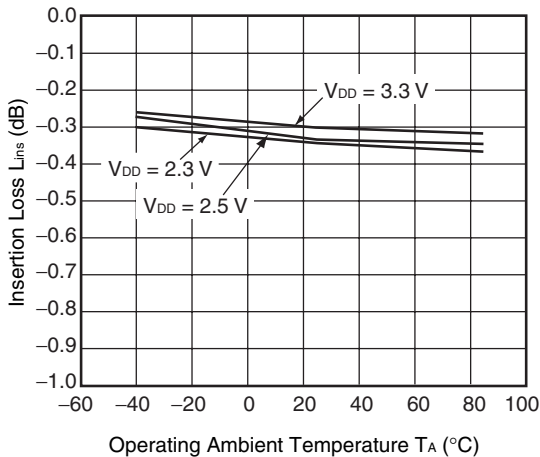
RFC-RF1/RF2/RF3/RF4 2nd HARMONICS vs.
INPUT POWER $f = 2$ GHz



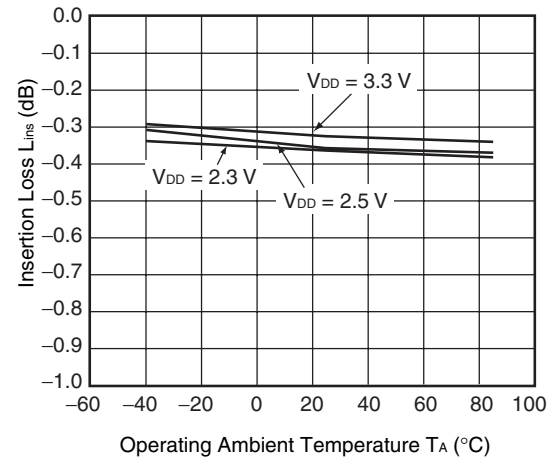
RFC-RF1/RF2/RF3/RF4 3rd HARMONICS $3f_o$ vs.
INPUT POWER $f = 2$ GHz



RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 0.5$ GHz

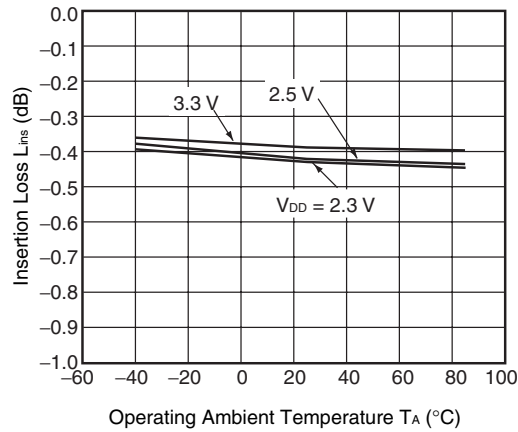


RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 1$ GHz

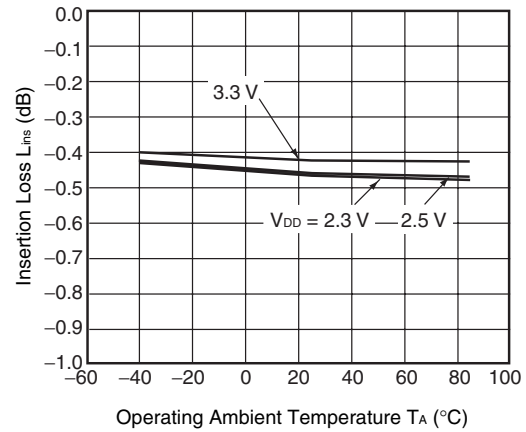


Remark The graphs indicate nominal characteristics.

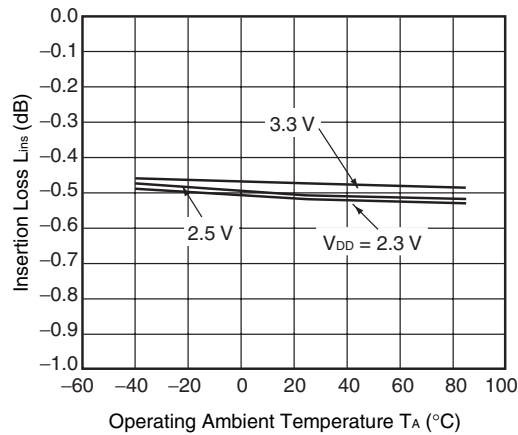
RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 2 \text{ GHz}$



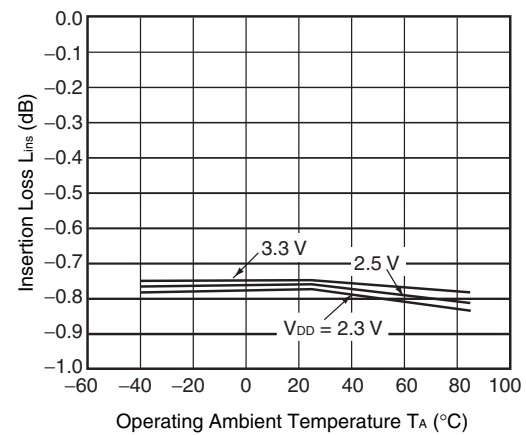
RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 2.7 \text{ GHz}$



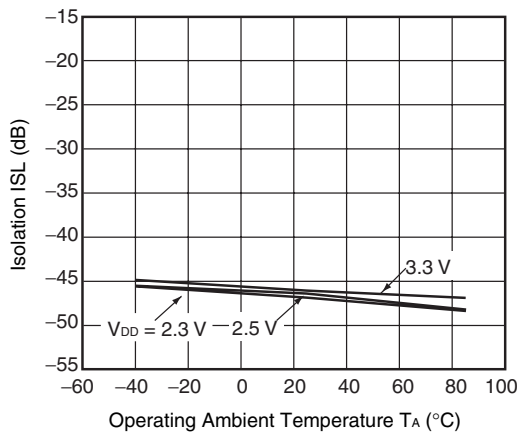
RFC-RF1/RF2/RF3/RF4 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 3.8 \text{ GHz}$



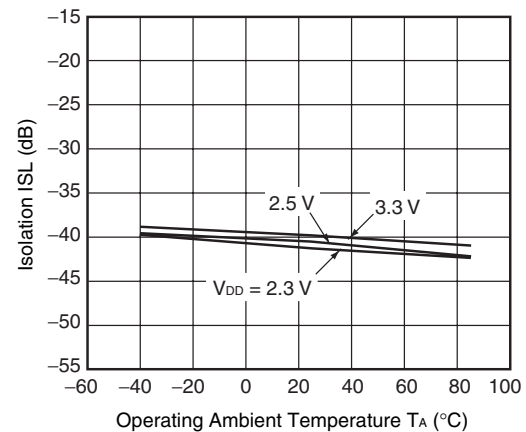
RFC-RF1 INSERTION LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 6 \text{ GHz}$



RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 0.5 \text{ GHz}$

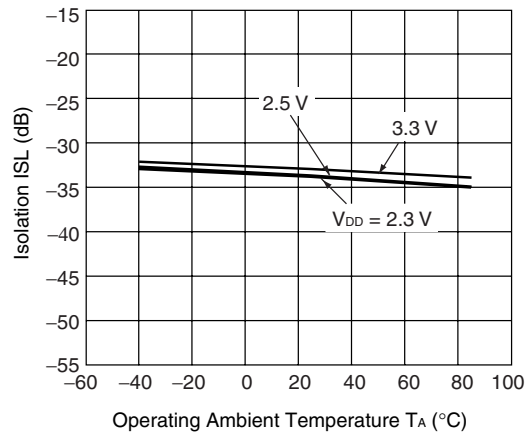


RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 1 \text{ GHz}$

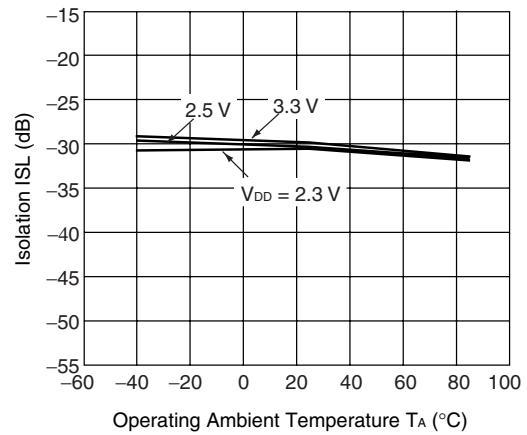


Remark The graphs indicate nominal characteristics.

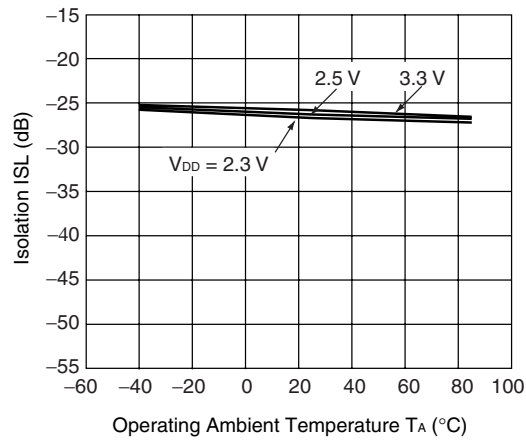
**RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 2$ GHz**



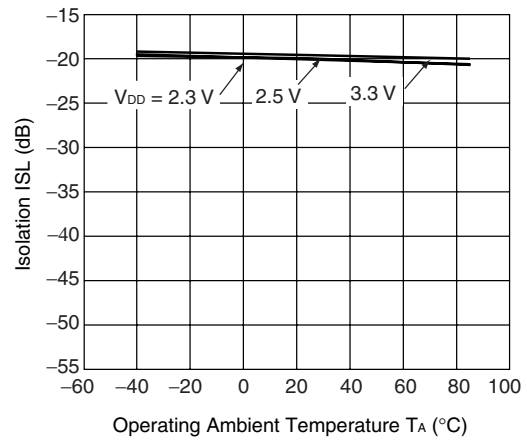
**RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 2.7$ GHz**



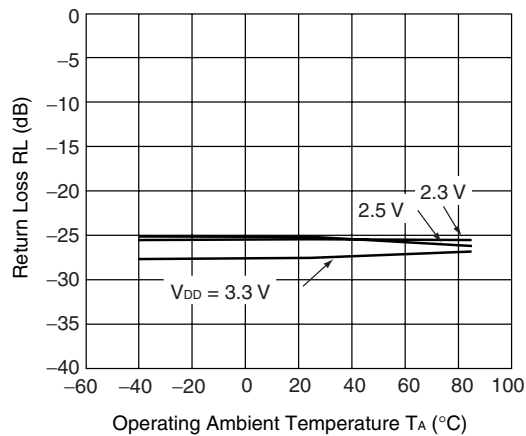
**RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 3.8$ GHz**



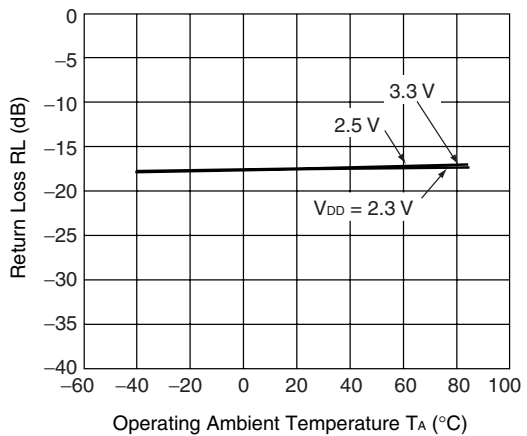
**RFC-RF1/RF2/RF3/RF4 ISOLATION vs.
OPERATING AMBIENT TEMPERATURE $f = 6$ GHz**



**RFC RETURN LOSS vs. OPERATING AMBIENT
TEMPERATURE $f = 3.8$ GHz**

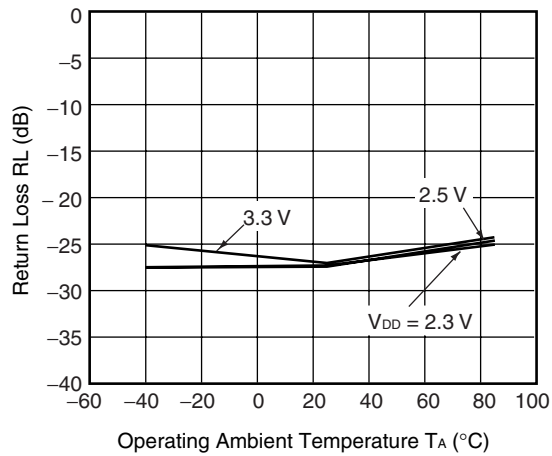


**RFC RETURN LOSS vs. OPERATING AMBIENT
TEMPERATURE $f = 6.0$ GHz**

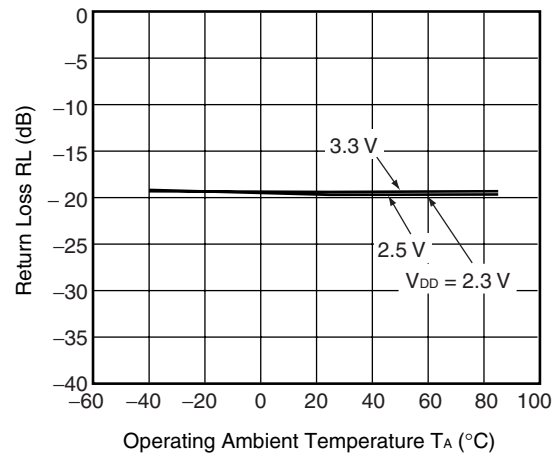


Remark The graphs indicate nominal characteristics.

RF 1/RF2/RF3/RF4 RETURN LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 3.8 \text{ GHz}$



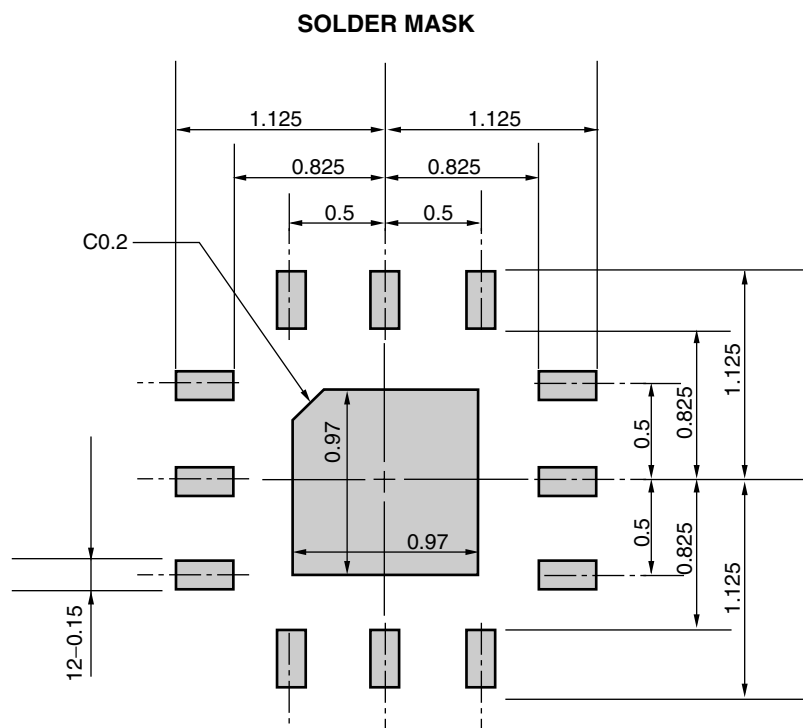
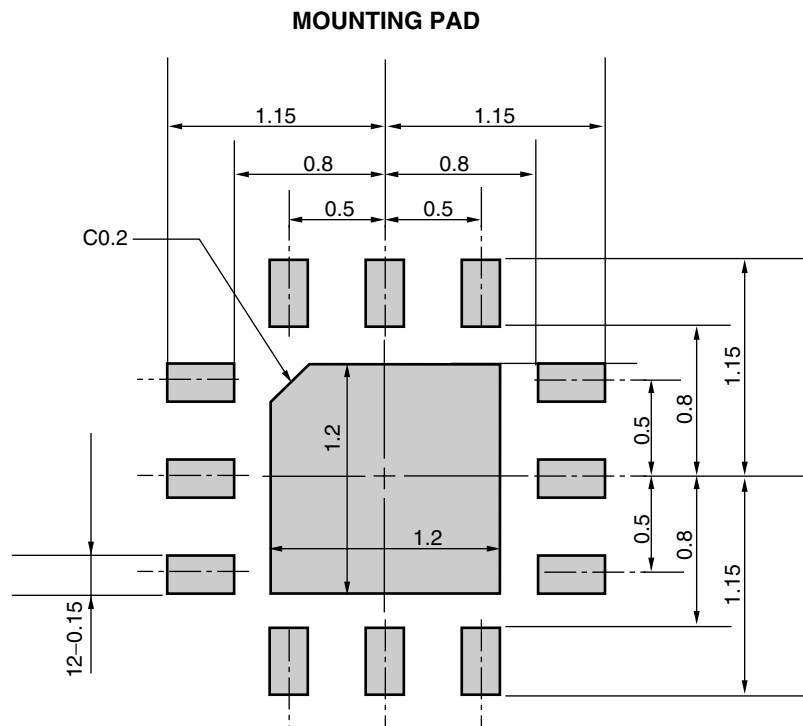
RRF1/RF2/RF3/RF4 RETURN LOSS vs.
OPERATING AMBIENT TEMPERATURE $f = 6 \text{ GHz}$



Remark The graphs indicate nominal characteristics.

MOUNTING PAD LAYOUT DIMENSIONS

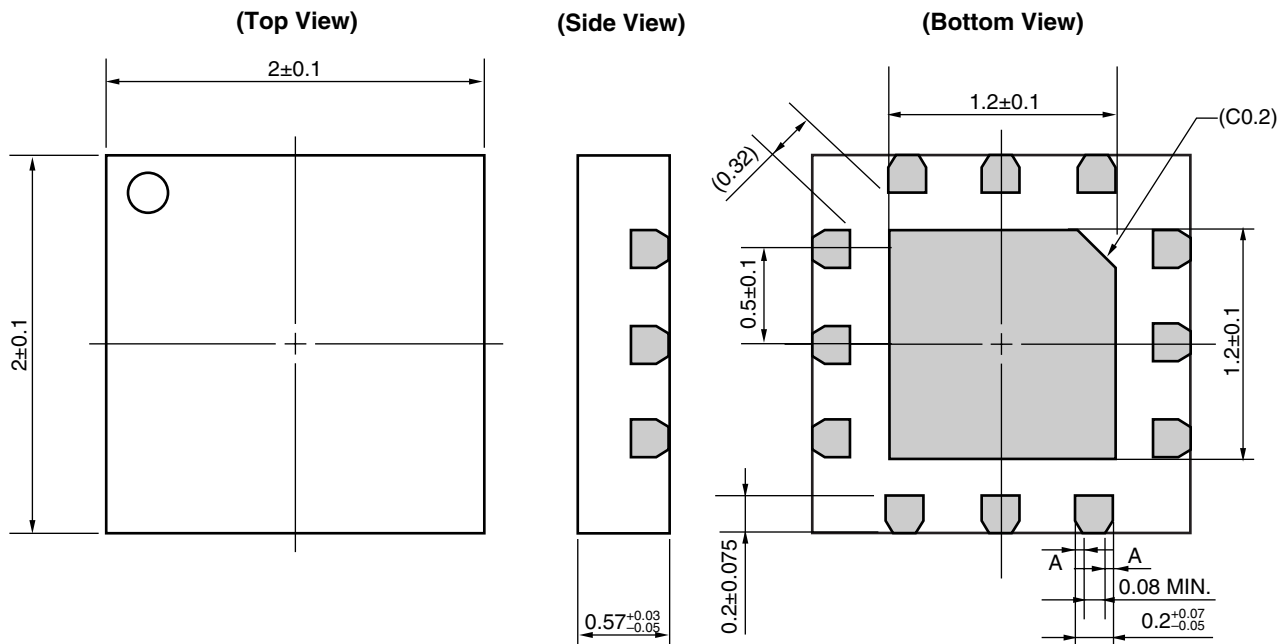
12-PIN PLASTIC QFN (T7K) (UNIT: mm)



Solder thickness : 0.1 mm

Remark The mounting pad layout in this document is for reference only.

When designing PCB, please consider workability of mounting, solder joint reliability, prevention of solder bridge and so on, in order to optimize the design.

PACKAGE DIMENSIONS**12-PIN PLASTIC QFN (T7K) (UNIT: mm)****Remark** $A > 0$

(): Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2% (Wt.) or below	IR260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2% (Wt.) or below	HS350

CAUTION

Do not use different soldering methods together (except for partial heating).

Revision History	μPD5904T7K Data Sheet
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Rev.	Date	Description	
		Page	Summary
1.00	Jul 24, 2012	–	First edition issued
2.00	Dec 11, 2012	p.2	GND is added as Pin No.13 in PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM.
		p.5	GND is added in EVALUATION CIRCUIT.

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